

REMARKS

This Amendment seeks to place this application in better form for allowance. The independent claims have been amended to address, among other things, the Examiner's concerns as expressed in a telephone interview on May 19, 2004.

Further, several of the claims have been amended to correct inadvertent typographical errors, to improve grammar and/or clarity, and to more definitely set forth the novel and unobvious features of Applicants' invention(s). No new matter has been added.

In addition, claims 51, 60 and 77, as amended, recite a substrate having a wafer or wafer-like shape. The specification, on page 9, lines 9-16 and on page 12, pages 3-10 (among others), describes the substrate, in one embodiment, having a wafer or wafer-like shape:

In one embodiment, the EIW is a wafer or wafer-like object. When the EIW is a wafer-like object, the EIW may have a different physical form factor than a product wafer. The processing equipment, however, may handle such an EIW without adverse modification to its hardware and/or software. For example, where an EIW includes circuitry, sensors and/or sources to monitor a CVD process, the EIW may have the same or substantially the same planar size and shape as a product wafer, but may be (slightly) thicker. As such, the EIW "behaves" like a thick wafer and the deposition equipment may handle the EIW with little or no modification to the equipment. ('433 app., page 9, lines 9-16).

The Sensor-EIW may also include circuitry and components that protrude from the surface, hence creating a portion that includes a non-flat surface topography. The circuitry and components are disposed on a wafer-like object that may be handled (automatically or manually) within the equipment. Thus, such an EIW includes a substrate that has a similar form factor and/or profile as a product wafer ('433 app., page 12, lines 3-10).

Notably, none of the amendments were motivated by patentability considerations in view of prior art, including the art cited or reference herein. Rather, Applicants have incorporated certain limitations into the independent claims in an effort to advance the prosecution of this application. Moreover, no new matter has been added.

Finally, in this preliminary amendment, three claims have been deleted (i.e., claims 52, 65 and 78) and three new claims have been added (i.e., claims 94, 95 and 96). As such, no fee is required.

CONCLUSION

Applicants respectfully request entry of the foregoing amendment. Applicants submit that all of the claims present patentable subject matter. Accordingly, Applicants respectfully request allowance of all of the claims.

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Respectfully submitted,



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